



Advance Product Change Notification

201808025A

Issue Date: 09-Sep-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online



QUALITY

Management Summary

NXP announces a change from silver filled epoxy to a sintered silver die attach for passive components in TO270WB packages.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

IMPROVED PASSIVE COMPONENT ATTACH MATERIAL FOR TO270WB PACKAGES

Description of Change

NXP announces a change from silver filled epoxy to a sintered silver die attach for passive components in TO270WB packages. Sintered silver is a widely accepted die attach material for power devices with superior thermal and electrical properties and significantly increases the adhesion strength of the bond between passive component and heatsink. Datasheet Functional Table RF performance specifications remains unchanged. Sample availability in Sept 2018. Electrical and reliability data will be available in late Sept 2018. If you have any questions or require additional information, please contact your local NXP sales office or NXP approved distributor.

Reason for Change

Die attach material standardization and improved die attach bond strength.

Identification of Affected Products

Device marking will not change. Date code of implementation will vary by device.

Product Availability

Sample Information

Samples are available from 28-Sep-2018

Production

Planned first shipment 14-Mar-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
No impact on form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 07-Dec-2018.

The Final PCN is planned to be issued on: 14-Dec-2018.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 09-Oct-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number

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